PCN# : P2BEA
Issue Date : Jan. 09, 2013

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

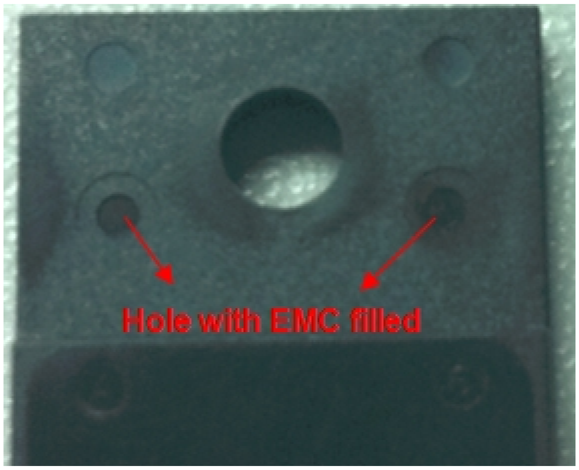
Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

Implementation of change:

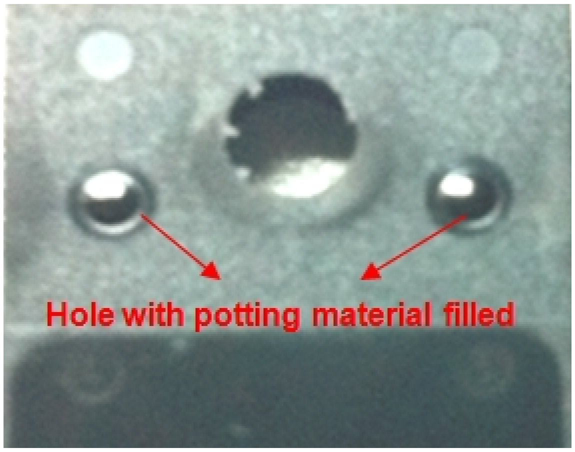
Expected First Shipment Date for Changed Product : Dec. 30, 2012

Expected First Date Code of Changed Product :1302

Description of Change (From) :
For TO3PF-3L package assembly in FSSZ
Retract mold type: hole with EMC filled.



Description of Change (To) :
Add alternative type of potting: hole with potting material(epoxy) filled.



Reason for Change:

The change applied to all the TO3PF-3L product assembly in Fairchild Semiconductor, Suzhou.

Product quality was enhanced a lot of isolation performance.The change also help to improve mold process productivity.

Affected Product(s):

FFAF60UA60DN	FGAF20N60SMD	FGAF40N60SMD
FGAF40N60UFDTU	FGAF40N60UFTU	FJAF4210OTU
FJAF4210RTU	FJAF4210YTU	FJAF4310OTU
FJAF4310YTU	FJAF6810ATU	FJAF6810DTU
FJAF6810TU	FJAFS1510ATU	FQAF11N90C
FQAF13N80	FQAF16N50	IRFS450B
SGF23N60UFTU	SGF5N150UFTU	SGF80N60UFTU
TIP147FTU		